

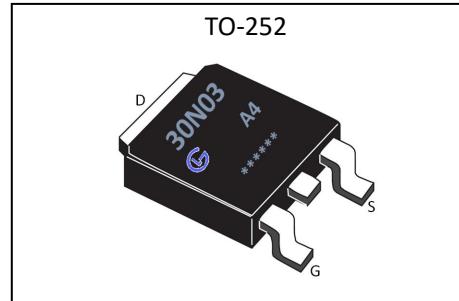
General Description

The GL30N03A4 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is TO-252, which accords with the RoHS standard.

V_{DSS}	30	V
I_D	30	A
P_D	40	W
$R_{DS(ON)type}$	10	$m\Omega$

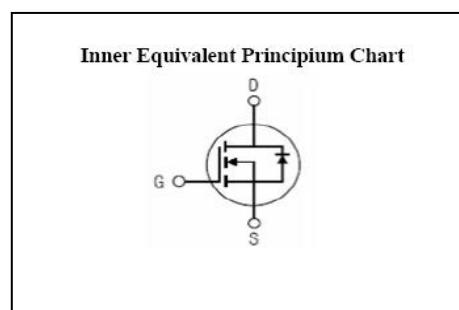
Features

- $R_{DS(ON)} < 14m\Omega$ @ $V_{GS}=10V$ (Typ:10mΩ)
- High density cell design for ultra low $R_{ds(on)}$
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation



Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Absolute ($T_c = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	30	V
I_D	Continuous Drain Current	30	A
I_{DM}	Pulsed Drain Current ^{a1}	80	A
V_{GS}	Gate-to-Source Voltage	± 20	V
P_D	Power Dissipation	40	W
E_{AS}	Single pulse avalanche energy ^{a5}	72	mJ
T_J, T_{stg}	Operating Junction and Storage Temperature Range	175, -55 to 175	°C

Caution :Stresses greater than those in the "Absolute Maximum Ratings" may cause permanent damage to the device



GL30N03A4

GL Silicon N-Channel Power MOSFET

Electrical Characteristics (Tc= 25°C unless otherwise specified)

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V _{DSS}	Drain to Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	--	--	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =30V, V _{GS} = 0V, T _a = 25°C	--	--	1.0	μA
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =+20V	--	--	0.1	μA
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =-20V	--	--	-0.1	μA

ON Characteristics ^{a3}						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R _{DSON}	Drain-to-Source On-Resistance	V _{GS} =10V, I _D =20A	--	10	15	mΩ
R _{DSON}	Drain-to-Source On-Resistance	V _{GS} =4.5V, I _D =15A	--	13	25	mΩ
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.5	V
Pulse width tp≤380μs, δ≤2%						

Dynamic Characteristics ^{a4}						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =20A	26	--	--	S
C _{iss}	Input Capacitance		--	938	--	pF
C _{oss}	Output Capacitance	V _{GS} =0V, V _{DS} =15V f=1.0MHz	--	142	--	
C _{rss}	Reverse Transfer Capacitance		--	99	--	

Resistive Switching Characteristics ^{a4}						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t _{d(ON)}	Turn-on Delay Time		--	5	--	ns
t _r	Rise Time	R _L =0.75Ω, V _{DD} =15V	--	12	--	
t _{d(OFF)}	Turn-Off Delay Time	V _{GS} =10V, R _G =3.0Ω	--	19	--	
t _f	Fall Time		--	6	--	
Q _g	Total Gate Charge		--	17.5	--	nC
Q _{gs}	Gate to Source Charge	I _D =20A, V _{DD} =15V	--	3.0	--	
Q _{gd}	Gate to Drain ("Miller")Charge	V _{GS} =10V	--	4.1	--	



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Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_S	Continuous Source Current ^{a2} (Body Diode)		--	--	30	A
V_{SD}	Diode Forward Voltage ^{a3}	$I_S=20A, V_{GS}=0V$	--	--	1.2	V

Thermal Characteristics

Symbol	Parameter	Typ.	Units
$R_{\theta JC}$	Junction-to-Case ^{a2}	3.125	°C/W

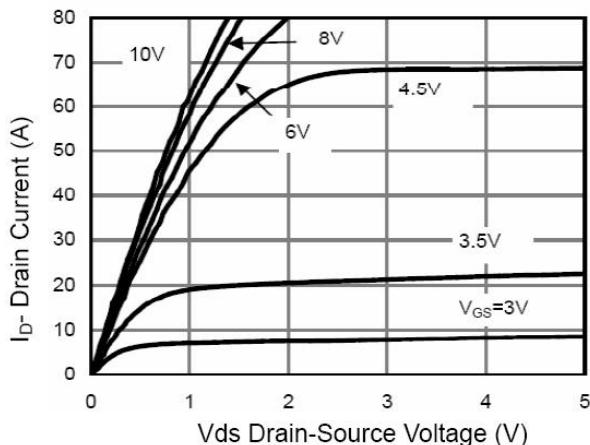
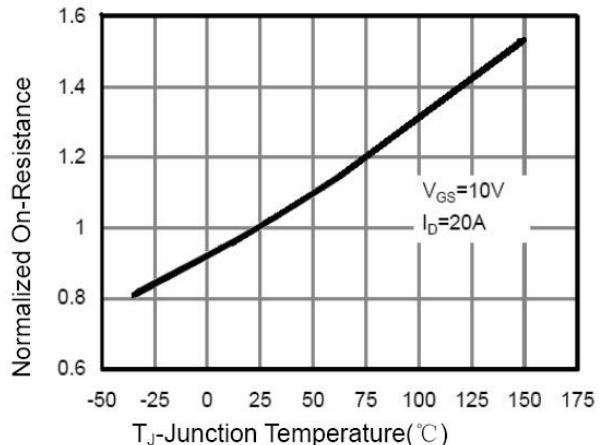
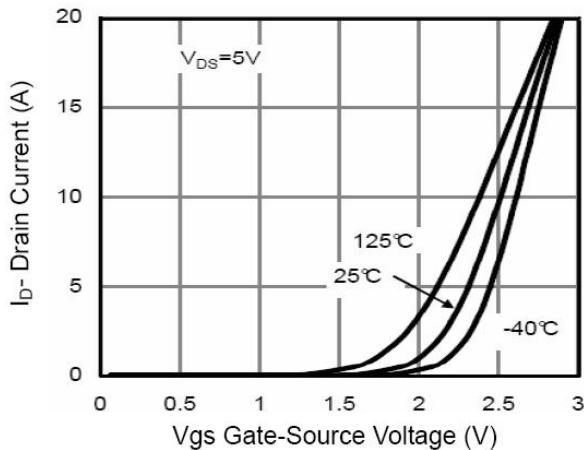
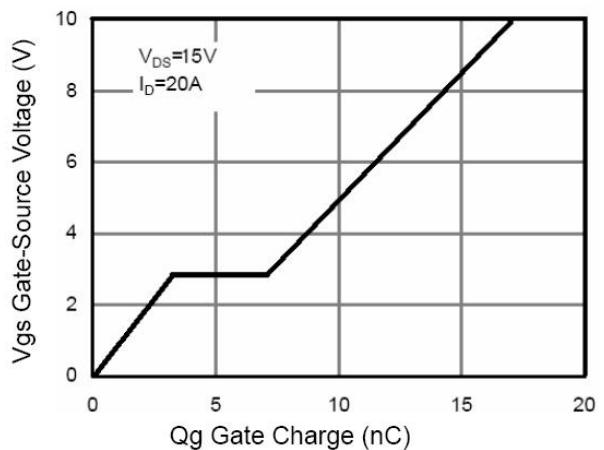
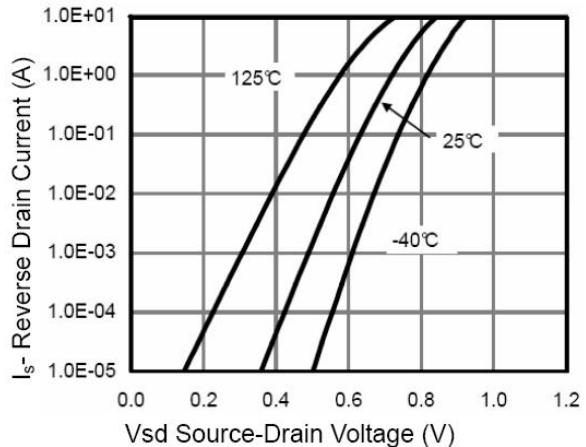
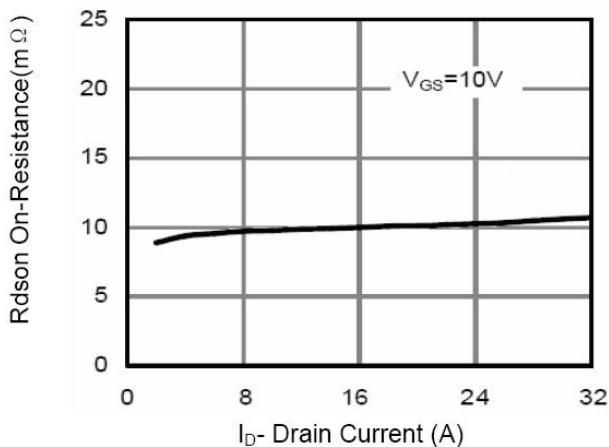
^{a1}: Repetitive Rating: Pulse width limited by maximum junction temperature.

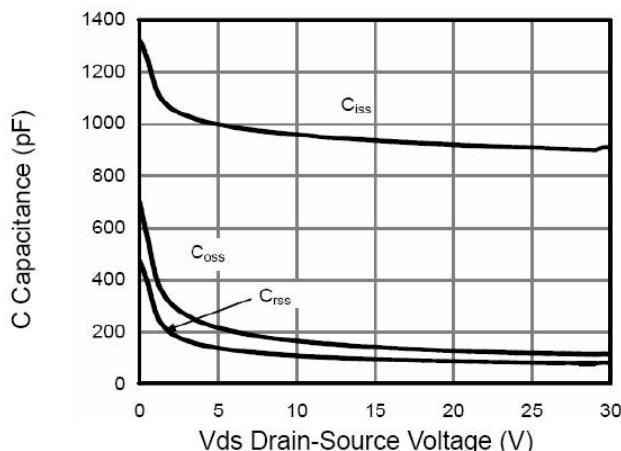
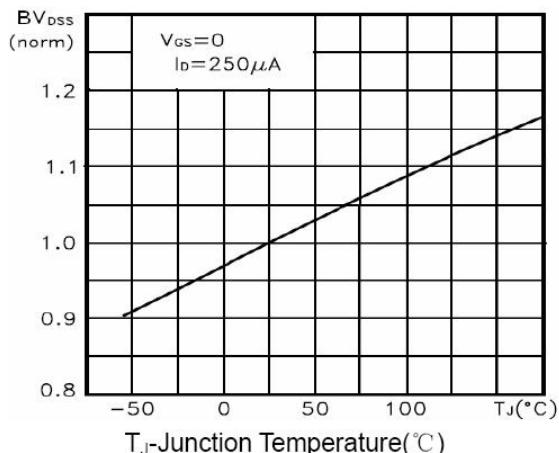
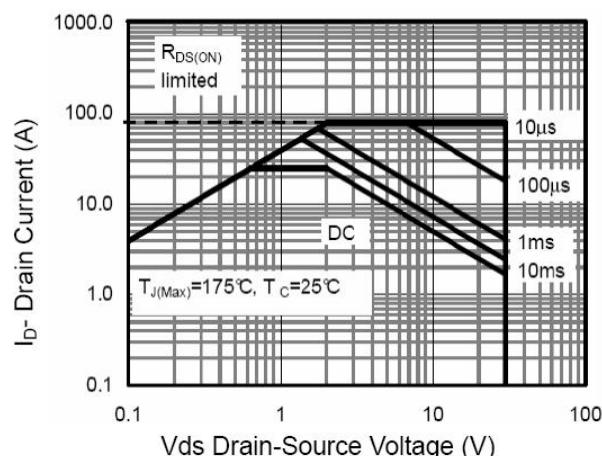
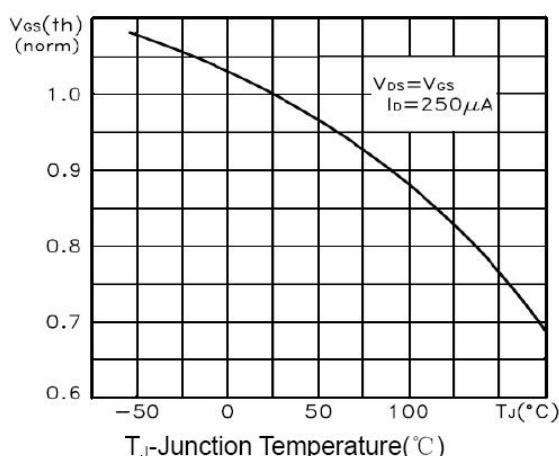
^{a2}: Surface Mounted on FR4 Board, $t \leq 10\text{sec}$.

^{a3}: Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

^{a4}: Guaranteed by design, not subject to production

^{a5}: EAS condition: $T_j=25^\circ\text{C}, VDD=30\text{V}, VG=10\text{V}, L=0.5\text{mH}, Rg=25\Omega$

Characteristics Curves

Figure 1 Output Characteristics

Figure 4 Rdson-Junction Temperature

Figure 2 Transfer Characteristics

Figure 5 Gate Charge



Figure 7 Capacitance vs Vds

Figure 9 BV_{DSS} vs Junction Temperature

Figure 8 Safe Operation Area

Figure 10 V_{GS(th)} vs Junction Temperature
